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# TLE4968-1M

High Precision Automotive Hall Effect Switch

## Data Sheet

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Page or Item	Subjects (major changes since previous revision)
<b>Revision 1.0, 2013-04-07</b>	

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# 1 Product Description



## 1.1 Overview

Characteristic	Supply Voltage	Supply Current	Sensitivity	Interface	Temperature
Bipolar Hall Effect Switch	3.0~32 V	1.6 mA	High B <sub>OP</sub> :1 mT B <sub>RP</sub> :-1 mT	Open Drain Output	-40°C to 170°C



Figure 1-1 Image of TLE4968-1M in the PG-SOT23-3-15 Package

## 1.2 Features

- 3.0 V to 32 V operating supply voltage
- Operation from unregulated power supply
- Reverse polarity protection (-18 V)
- Overvoltage capability up to 42 V without external resistor
- Output overcurrent & overtemperature protection
- Active error compensation
- High stability of magnetic thresholds
- Low jitter (typ. 0.35 μs)
- High ESD performance
- Small SMD package PG-SOT23-3-15 (TLE4968-1M)

## 1.3 Target Applications

Target applications for the TLE496x Hall switch family are all applications which require a high precision Hall switch with an operating temperature range from -40°C to 170°C. Its superior supply voltage range from 3.0 V to 32 V with overvoltage capability (e.g. load-dump) up to 42 V without external resistor makes it ideally suited for automotive and industrial applications.

The TLE4968-1M has very low magnetic thresholds and a bipolar switching behavior. It is therefore especially suited for applications which require a high sensitivity device and an output switching close to zero magnetic field values. Possible applications are BLDC rotor position measurement or speed and position measurements in camshaft or transmission applications.

Table 1-1 Ordering Information

Product Name	Product Type	Ordering Code	Package
TLE4968-1M	Bipolar Hall Switch	SP000923334	PG-SOT23-3-15



## 2 Functional Description

### 2.1 General

The TLE4968-1M is an integrated Hall effect switch designed specifically for highly accurate applications with superior supply voltage capability, operating temperature range and temperature stability of the magnetic thresholds.

### 2.2 Pin Configuration (top view)

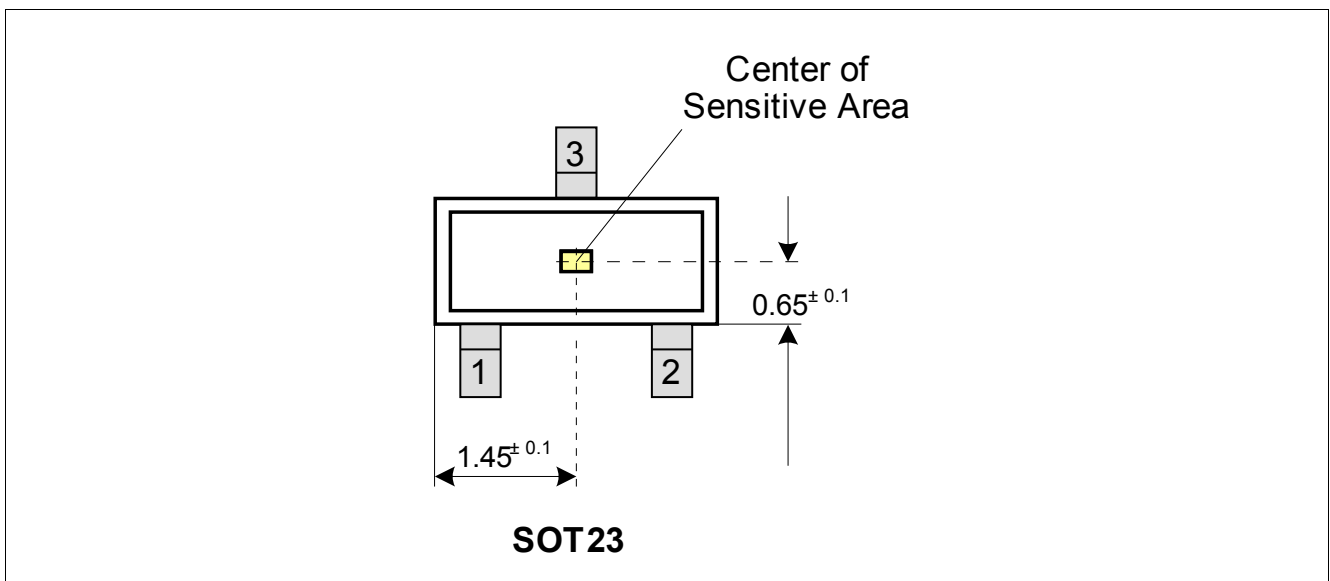


Figure 2-1 Pin Configuration and Center of Sensitive Area

### 2.3 Pin Description

Table 2-1 Pin Description PG-SOT23-3-15

Pin No.	Symbol	Function
1	VDD	Supply voltage
2	Q	Output
3	GND	Ground

## 2.4 Block Diagram

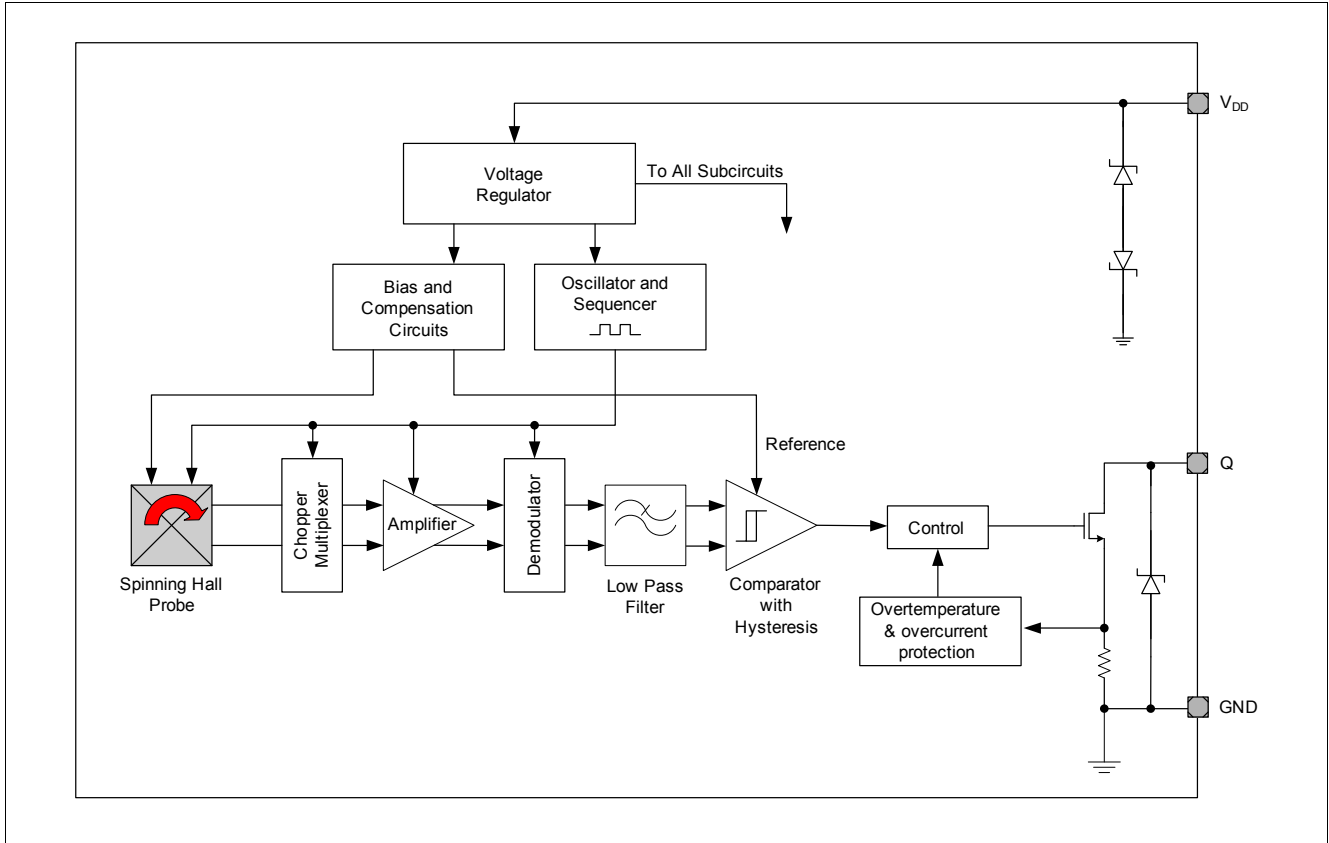


Figure 2-2 Functional Block Diagram TLE4968-1M

## 2.5 Functional Block Description

The chopped Hall IC switch comprises a Hall probe, bias generator, compensation circuits, oscillator and output transistor.

The bias generator provides currents for the Hall probe and the active circuits. Compensation circuits stabilize the temperature behavior and reduce influence of technology variations.

The active error compensation (chopping technique) rejects offsets in the signal path and the influence of mechanical stress to the Hall probe caused by molding and soldering processes and other thermal stress in the package. The chopped measurement principle together with the threshold generator and the comparator ensures highly accurate and temperature stable magnetic thresholds.

The output transistor has an integrated overcurrent and overtemperature protection.

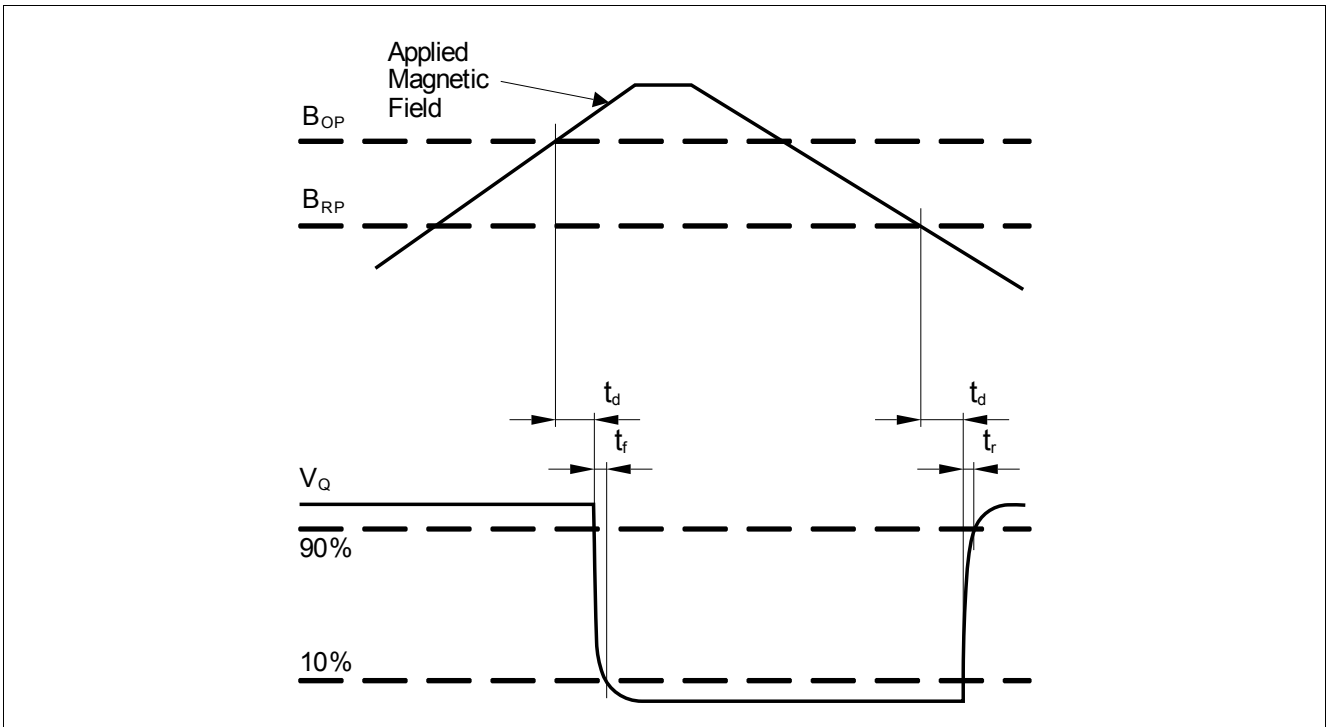


Figure 2-3 Timing Diagram TLE4968-1M

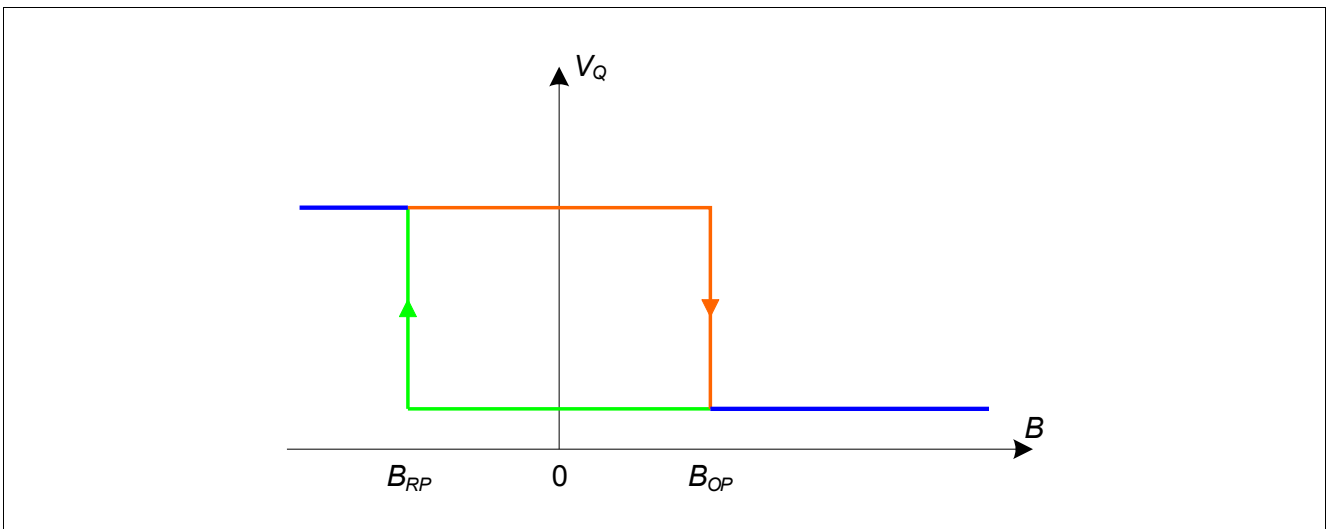


Figure 2-4 Output Signal TLE4968-1M

## 2.6 Start-up Behavior

The magnetic thresholds exhibit a hysteresis  $B_{HYS} = B_{OP} - B_{RP}$ . In case of a power-on with a magnetic field  $B$  within hysteresis ( $B_{OP} > B > B_{RP}$ ) the output of the sensor is set to the pull up voltage level ( $V_Q$ ) per default. After the first crossing of  $B_{OP}$  or  $B_{RP}$  of the magnetic field the internal decision logic is set to the corresponding magnetic input value.

This means for  $B > B_{OP}$  the output is switching, for  $B < B_{RP}$  and  $B_{OP} > B > B_{RP}$  the output stays at  $V_Q$ .

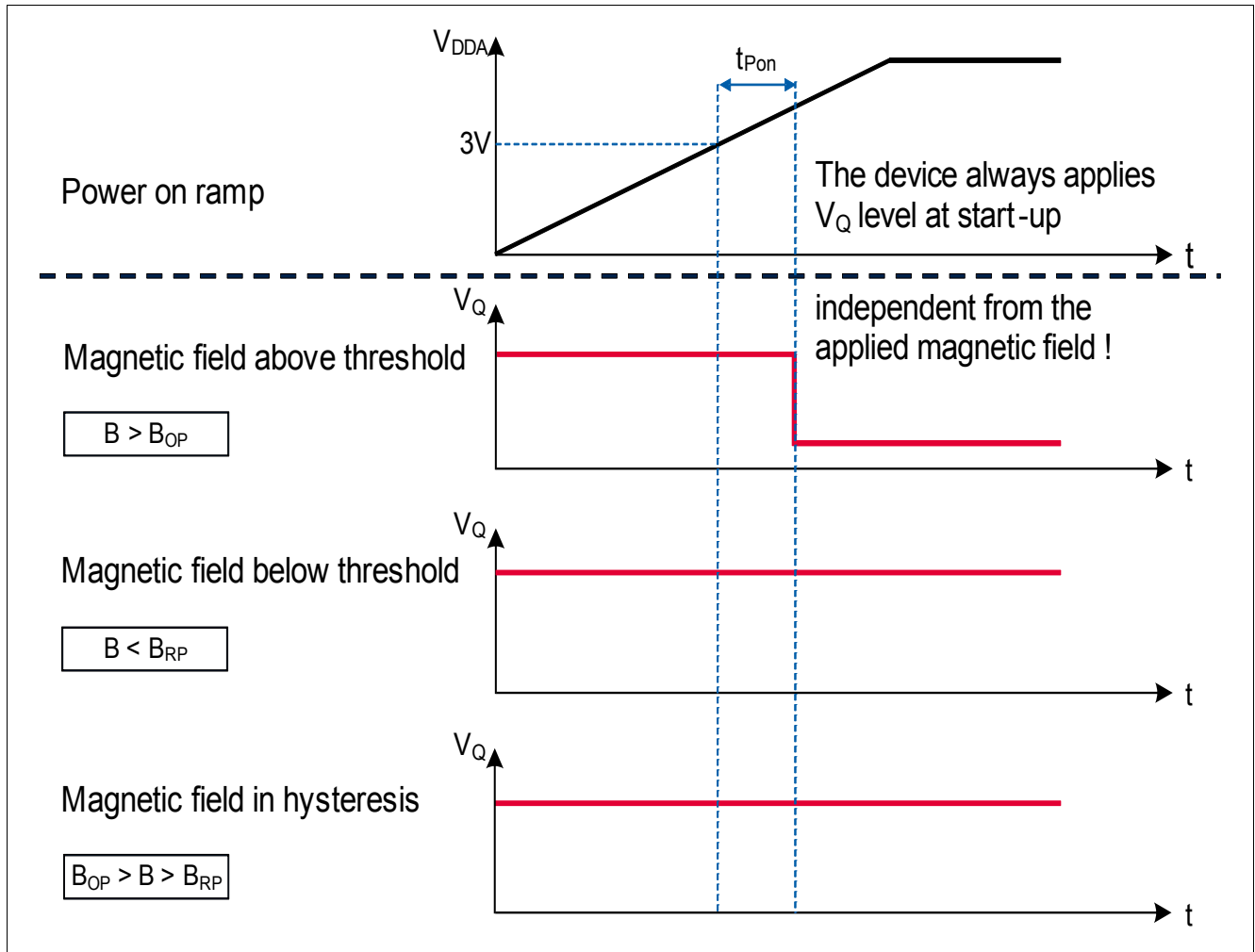


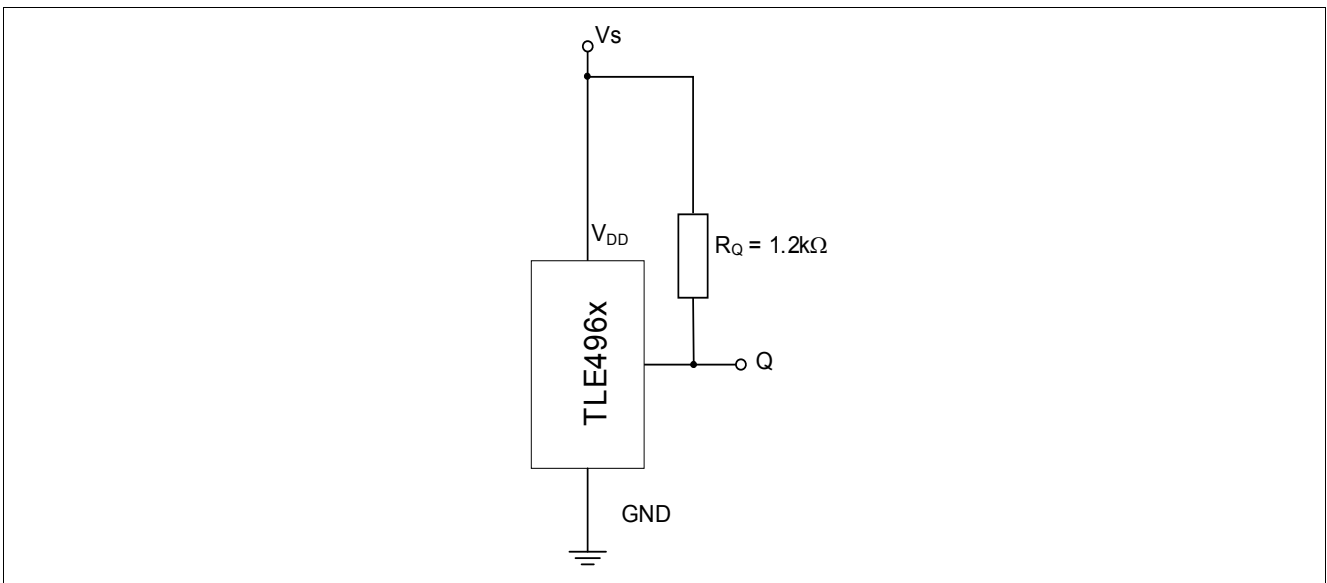
Figure 2-5 Illustration of the Start-up Behavior of the TLE4968-1M

### 3 Specification

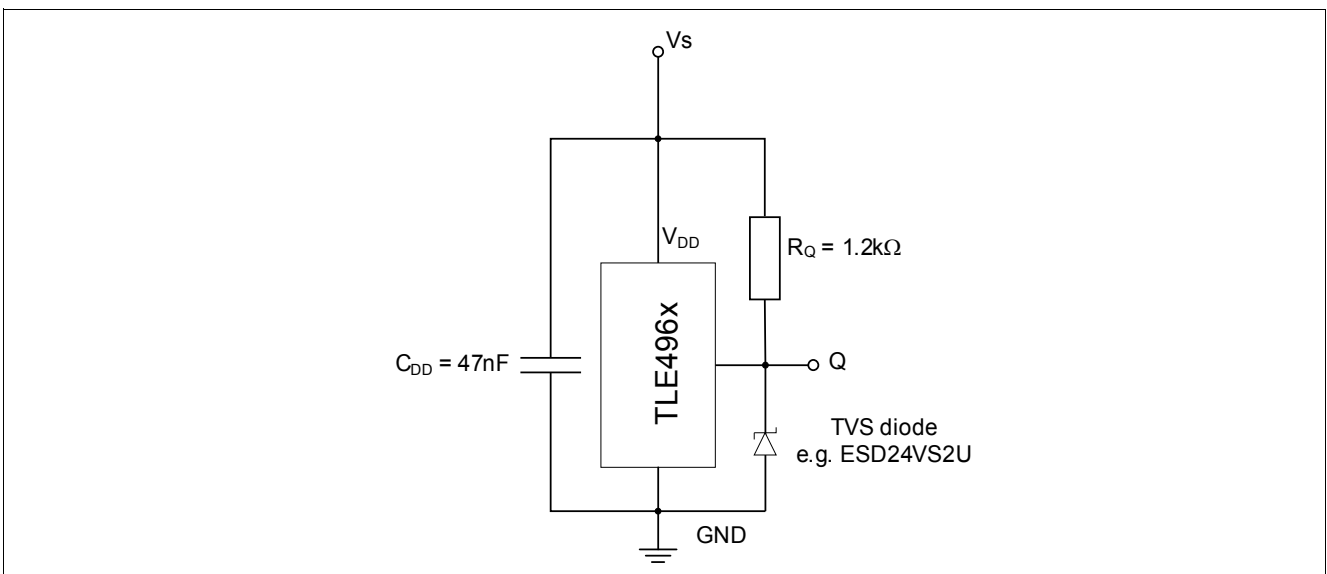
#### 3.1 Application Circuit

The following **Figure 3-1** shows the basic option of an application circuit. Only a pull-up resistor  $R_Q$  is necessary. An external series resistor for  $V_S$  is not needed. The resistor  $R_Q$  has to be in a dimension to match the applied  $V_S$  to keep  $I_Q$  limited to the operating range of maximum 25 mA.

e.g.:  $V_S = 12\text{ V}$ ;  $I_Q = 12\text{ V}/1200\ \Omega = 10\text{ mA}$



**Figure 3-1 Basic Application Circuit #1: Only Pull-Up Resistor is necessary**



**Figure 3-2 Enhanced Application Circuit #2 for extended ESD robustness**

With an additional capacitor  $C_{DD}$  and a transient voltage suppression (TVS) diode an extended ESD robustness of 15kV on system level is achieved (**Figure 3-2**). If an increased robustness for e.g. testpulse 1 is required, a serial resistor in the supply needs to be added (see also **Chapter 3.5**).

### 3.2 Absolute Maximum Ratings

**Table 3-1 Absolute Maximum Rating Parameters**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Supply voltage <sup>1)</sup>	V <sub>DD</sub>	-18		32 42	V	10h, no external resistor required
Output voltage	V <sub>Q</sub>	-0.5		32	V	
Reverse output current	I <sub>Q</sub>	-70			mA	
Junction temperature <sup>1)</sup>	T <sub>J</sub>	-40		155 165 175 195	°C	for 2000h (not additive) for 1000h (not additive) for 168h (not additive) for 3 x 1h (additive)
Storage temperature	T <sub>S</sub>	-40		150	°C	
Thermal resistance Junction ambient	R <sub>thJA</sub>			300	K/W	for PG-SOT23-3-15 (2s2p)
Thermal resistance Junction lead	R <sub>thJL</sub>			100	K/W	for PG-SOT23-3-15

1) This lifetime statement is an anticipation based on an extrapolation of Infineon's qualification test results. The actual lifetime of a component depends on its form of application and type of use etc. and may deviate from such statement. The lifetime statement shall in no event extend the agreed warranty period.

**Attention: Stresses above the max. values listed here may cause permanent damage to the device. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. Maximum ratings are absolute ratings; exceeding only one of these values may cause irreversible damage to the integrated circuit.**

Calculation of the dissipated power P<sub>DIS</sub> and junction temperature T<sub>J</sub> of the chip (SOT23 example):

e.g for: V<sub>DD</sub> = 12 V, I<sub>S</sub> = 2.5 mA, V<sub>QSAT</sub> = 0.5 V, I<sub>Q</sub> = 20 mA

Power dissipation: P<sub>DIS</sub> = 12 V x 2.5 mA + 0.5 V x 20 mA = 30 mW + 10 mW = 40 mW

Temperature ΔT = R<sub>thJA</sub> x P<sub>DIS</sub> = 300 K/W x 40 mW = 12 K

For T<sub>A</sub> = 150 °C: T<sub>J</sub> = T<sub>A</sub> + ΔT = 150 °C + 12 K = 162 °C

**Table 3-2 ESD Protection<sup>1)</sup> (TA = 25°C)**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
ESD voltage (HBM) <sup>2)</sup>	V <sub>ESD</sub>	-7		7	kV	R = 1.5 kΩ, C = 100 pF  with circuit shown in <a href="#">Figure 3-2</a>
ESD voltage (SDM) <sup>3)</sup>		-1		1		
ESD voltage (system level) <sup>4)</sup>		-15		15		

1) Characterization of ESD is carried out on a sample basis, not subject to production test.

2) Human Body Model (HBM) tests according to EIA/JESD22-A114.

3) Socket device model (SDM) tests according to EOS/ESD-DS5.3-1993.

4) Gun test (2kΩ / 330pF or 330Ω / 150pF) according to ISO 10605-2008.

### 3.3 Operating Range

The following operating conditions must not be exceeded in order to ensure correct operation of the TLE4968-1M. All parameters specified in the following sections refer to these operating conditions unless otherwise mentioned.

**Table 3-3 Operating Conditions Parameters**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Supply voltage	$V_{DD}$	3.0		32 <sup>1)</sup>	V	
Output voltage	$V_Q$	-0.3		32	V	
Junction temperature	$T_j$	-40		170	°C	
Output current	$I_Q$	0		25	mA	
Magnetic signal input frequency <sup>2)</sup>	$f_{SW}$	0		10	kHz	

- 1) Latch-up test with factor 1.5 is not covered. Please see max ratings also.
- 2) For operation at the maximum switching frequency the magnetic input signal must be 1.4 times higher than for static fields. This is due to the -3dB corner frequency of the internal low-pass filter in the signal path.

### 3.4 Electrical and Magnetic Characteristics

Product characteristics involve the spread of values guaranteed within the specified voltage and ambient temperature range. Typical characteristics are the median of the production and correspond to  $V_{DD} = 12\text{ V}$  and  $T_A = 25^\circ\text{C}$ . The below listed specification is valid in combination with the application circuit shown in [Figure 3-1](#) and [Figure 3-2](#)

**Table 3-4 General Electrical Characteristics**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Supply current	$I_S$	1.1	1.6	2.5	mA	
Reverse current	$I_{SR}$		0.05	1	mA	for $V_{DD} = -18\text{ V}$
Output saturation voltage	$V_{QSAT}$		0.2	0.5	V	$I_Q = 20\text{ mA}$
			0.24	0.6	V	$I_Q = 25\text{ mA}$
Output leakage current	$I_{QLEAK}$			10	$\mu\text{A}$	
Output current limitation	$I_{QLIMIT}$	30	56	70	mA	internally limited & thermal shutdown
Output fall time <sup>1)</sup>	$t_f$	0.17	0.4	1	$\mu\text{s}$	1.2 k $\Omega$ / 50 pF, see <a href="#">Figure 2-3</a>
Output rise time <sup>1)</sup>	$t_r$	0.4	0.5	1	$\mu\text{s}$	1.2 k $\Omega$ / 50 pF, see <a href="#">Figure 2-3</a>
Output jitter <sup>1)2)</sup>	$t_{QJ}$		0.35	1	$\mu\text{s}$	For square wave signal with 1 kHz
Delay time <sup>1)3)</sup>	$t_d$	12	15	30	$\mu\text{s}$	see <a href="#">Figure 2-3</a>
Power-on time <sup>1)4)</sup>	$t_{PON}$		80	150	$\mu\text{s}$	$V_{DD} = 3\text{ V}$ , $B \leq B_{RP} - 0.5\text{ mT}$ or $B \geq B_{OP} + 0.5\text{ mT}$
Chopper frequency <sup>1)</sup>	$f_{OSC}$		350		kHz	

- 1) Not subject to production test, verified by design/characterization.
- 2) Output jitter is the  $1\sigma$  value of the output switching distribution.
- 3) Systematic delay between magnetic threshold reached and output switching.
- 4) Time from applying  $V_{DD} = 3.0\text{ V}$  to the sensor until the output is valid.

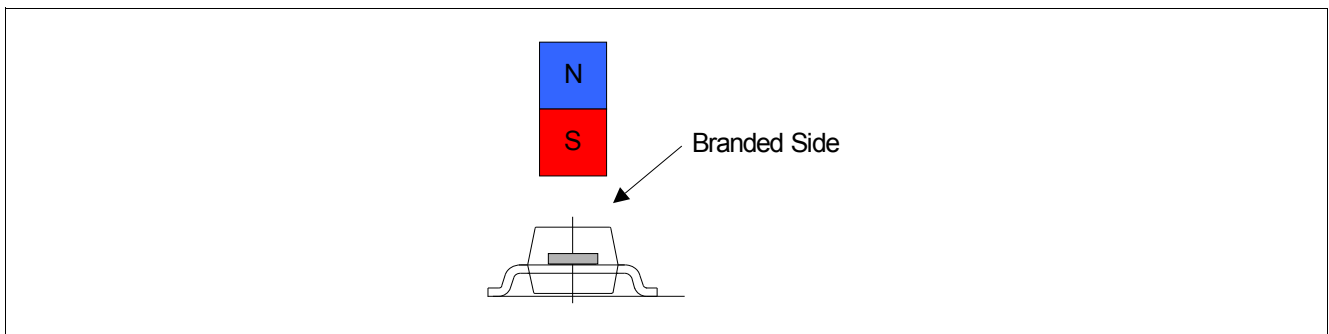
**Table 3-5 Magnetic Characteristics**

Parameter	Symbol	T (°C)	Values			Unit	Note / Test Condition
			Min.	Typ.	Max.		
Operating point	B <sub>OP</sub>	-40...170	-0.35	1.0	2.25	mT	
Release point	B <sub>RP</sub>	-40...170	-2.25	-1.0	0.35	mT	
Hysteresis	B <sub>HYS</sub>	-40...170	1.1	2.0	2.9	mT	
Effective noise value of the magnetic switching points <sup>1)</sup>	B <sub>Neff</sub>	25		62		μT	
Temperature compensation of magnetic thresholds <sup>2)</sup>	T <sub>C</sub>			0		ppm/K	

- 1) The magnetic noise is normal distributed and can be assumed as nearly independent to frequency without sampling noise or digital noise effects. The typical value represents a the rms-value and corresponds therefore to a 1 σ probability of normal distribution. Consequently a 3 σ value corresponds to 99.7% probability of appearance.
- 2) Not subject to production test, verified by design/characterization.

**Field Direction Definition**

Positive magnetic fields are defined with the south pole of the magnet to the branded side of package.



**Figure 3-3 Definition of Magnetic Field Direction PG-SOT23-3-15**



### 3.5 Electro Magnetic Compatibility

Characterization of Electro Magnetic Compatibility is carried out on a sample basis from one qualification lot. Not all specification parameters have been monitored during EMC exposure.

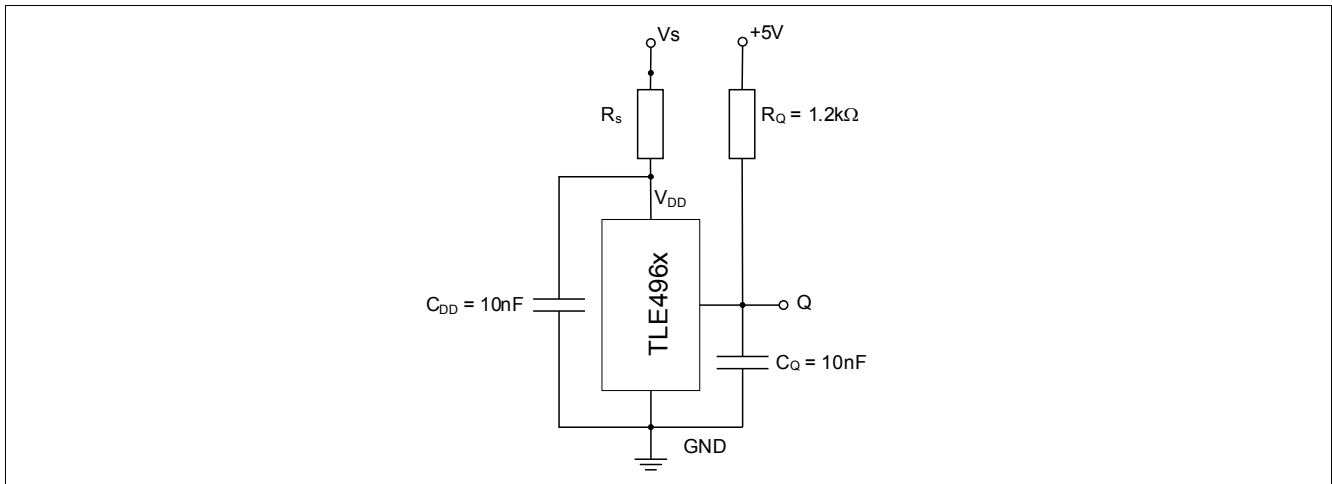


Figure 3-4 EMC Test Circuit

Ref: ISO 7637-2 (Version 2004), test circuit [Figure 3.4](#) (with external resistor,  $R_S = 100 \Omega$ )

Table 3-6 Magnetic Compatibility

Parameter	Symbol	Level / Type	Status
Testpulse 1	$V_{EMC}$	-100 V	C
Testpulse 2a <sup>1)</sup>		60 V/110 V	A/C
Testpulse 2b		10 V	C
Testpulse 3a		-150 V	A
Testpulse 3b		100 V	A
Testpulse 4 <sup>2)</sup>		-7 V / -5.5 V	A
Testpulse 5b <sup>3)</sup>		$U_S = 86.5 \text{ V} / U_S^* = 28.5 \text{ V}$	A

1) ISO 7637-2 (2004) describes internal resistance = 2  $\Omega$  (former 10  $\Omega$ ).

2) According to 7637-2 for test pulse 4 the test voltage shall be 12 V +/- 0.2 V.

3) A central load dump protection of 42 V is used.  $U_S^* = 42 \text{ V}$ -13.5 V.

Ref: ISO 7637-2 (Version 2004), test circuit [Figure 3.4](#) (without external resistor,  $R_S = 0\Omega$ )

Table 3-7 Electro Magnetic Compatibility

Parameter	Symbol	Level / Type	Status
Testpulse 1	$V_{EMC}$	-50 V	C
Testpulse 2a <sup>1)</sup>		50 V	A
Testpulse 2b		10 V	C
Testpulse 3a		-150 V	A
Testpulse 3b		100 V	A
Testpulse 4 <sup>2)</sup>		-7 V / 5.5 V	A
Testpulse 5b <sup>3)</sup>		$U_S = 86.5 \text{ V} / U_S^* = 28.5 \text{ V}$	A

1) ISO 7637-2 (2004) describes internal resistance = 2  $\Omega$  (former 10  $\Omega$ ).

2) According to 7637-2 for test pulse 4 the test voltage shall be 12 V +/- 0.2 V.

3) A central load dump protection of 42 V is used.  $U_S^* = 42 \text{ V}$ -13.5 V.

## 4 Package Information

The TLE4968-1M is available in the small halogen free SMD package PG-SOT23-3-15.

### 4.1 Package Outline PG-SOT23-3-15

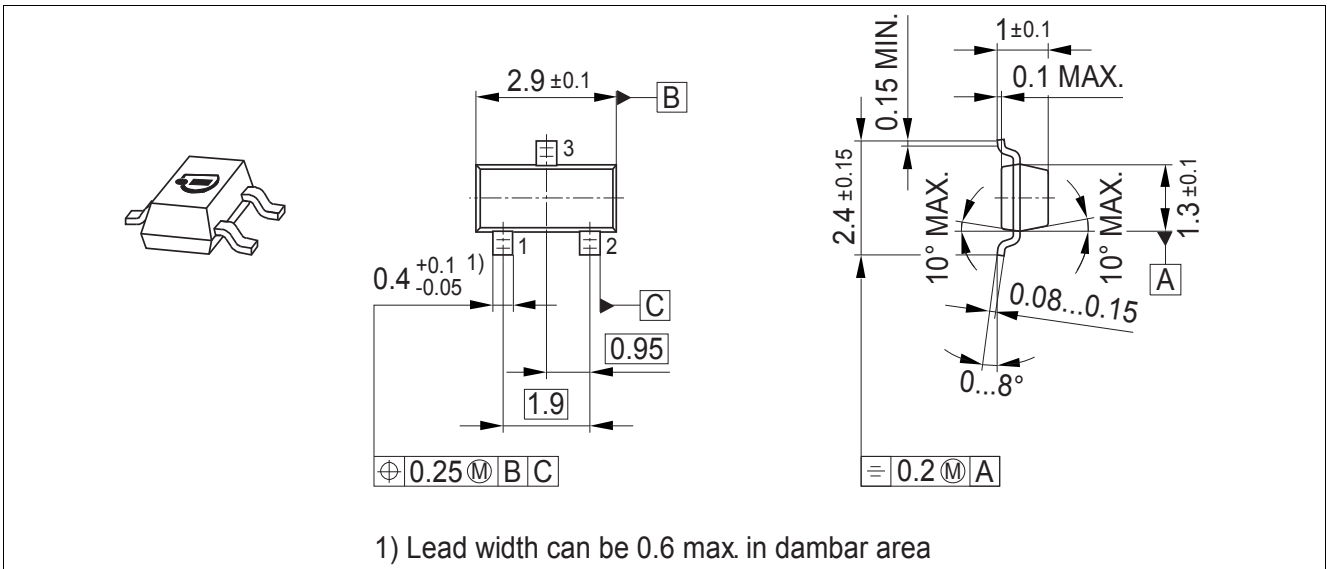


Figure 4-1 PG-SOT23-3-15 Package Outline (All Dimensions in mm)

### 4.2 Packing Information PG-SOT23-3-15

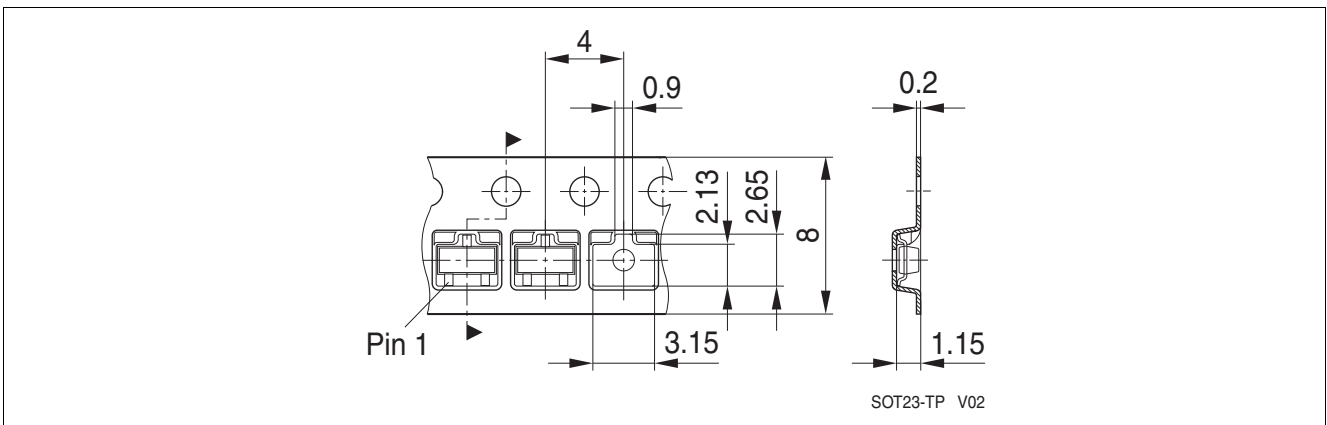


Figure 4-2 Packing of the PG-SOT23-3-15 in a Tape

### 4.3 Footprint PG-SC59-3-5 and PG-SOT23-3-15

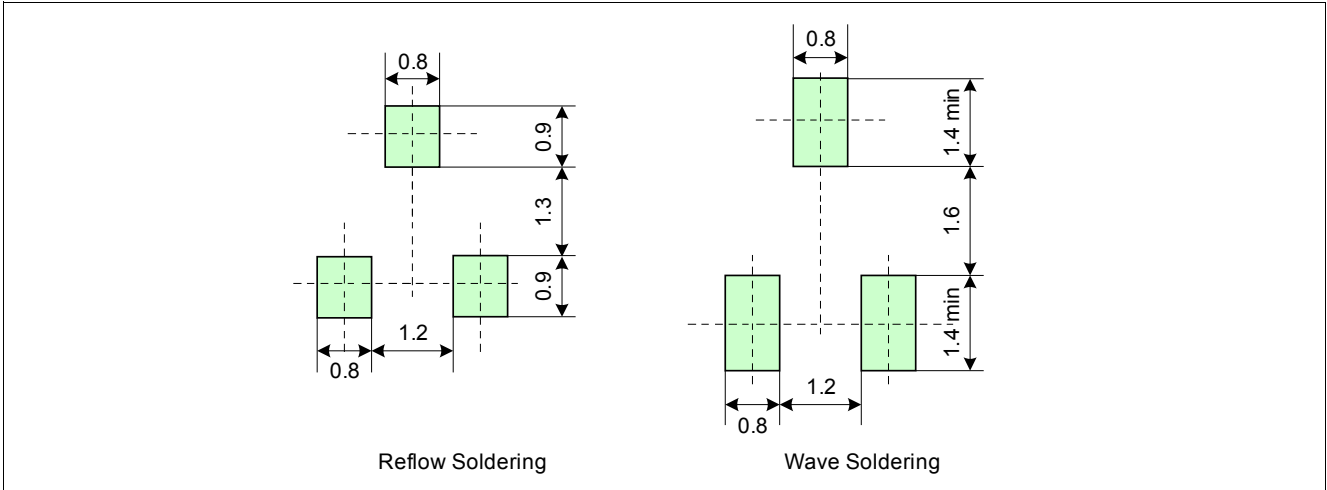


Figure 4-3 Footprint PG-SC59-3-5 and PG-SOT23-3-15

### 4.4 PG-SOT23-3-15 Distance between Chip and Package

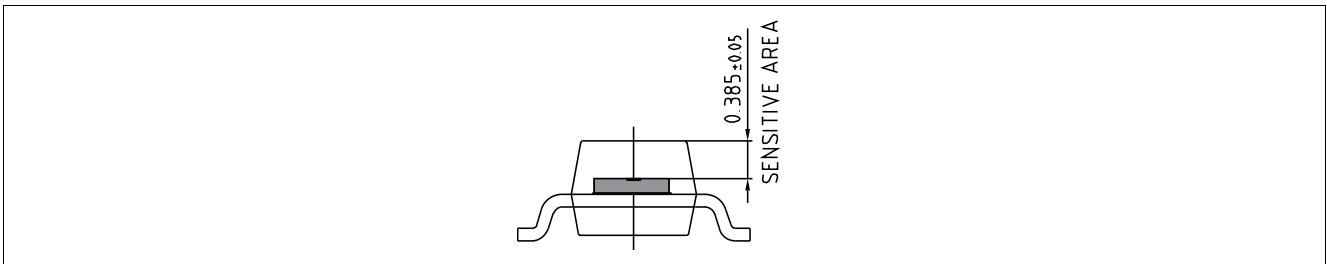


Figure 4-4 Distance between Chip and Package

### 4.5 Package Marking

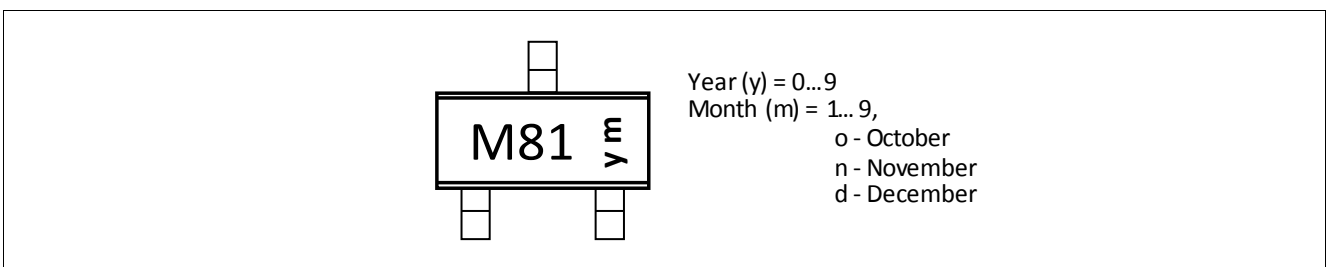


Figure 4-5 Marking of TLE4968-1M

## 5 Graphs of the Magnetic Parameters

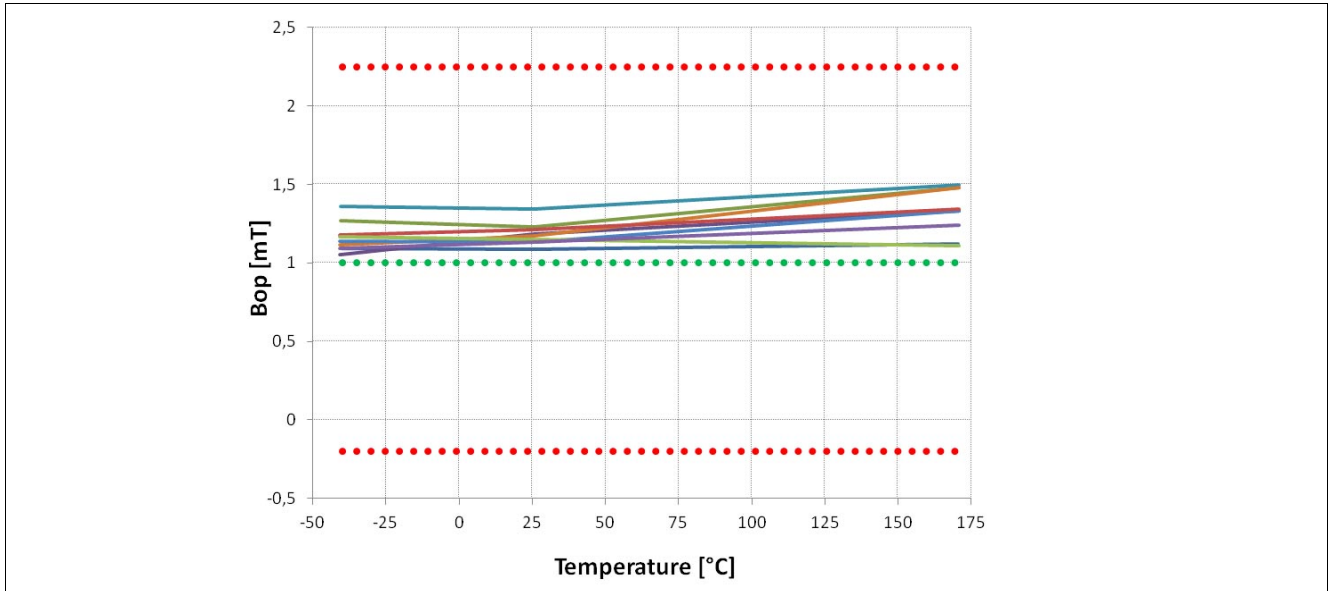


Figure 5-1 Operating Point ( $B_{OP}$ ) of the TLE4968-1M over Temperature

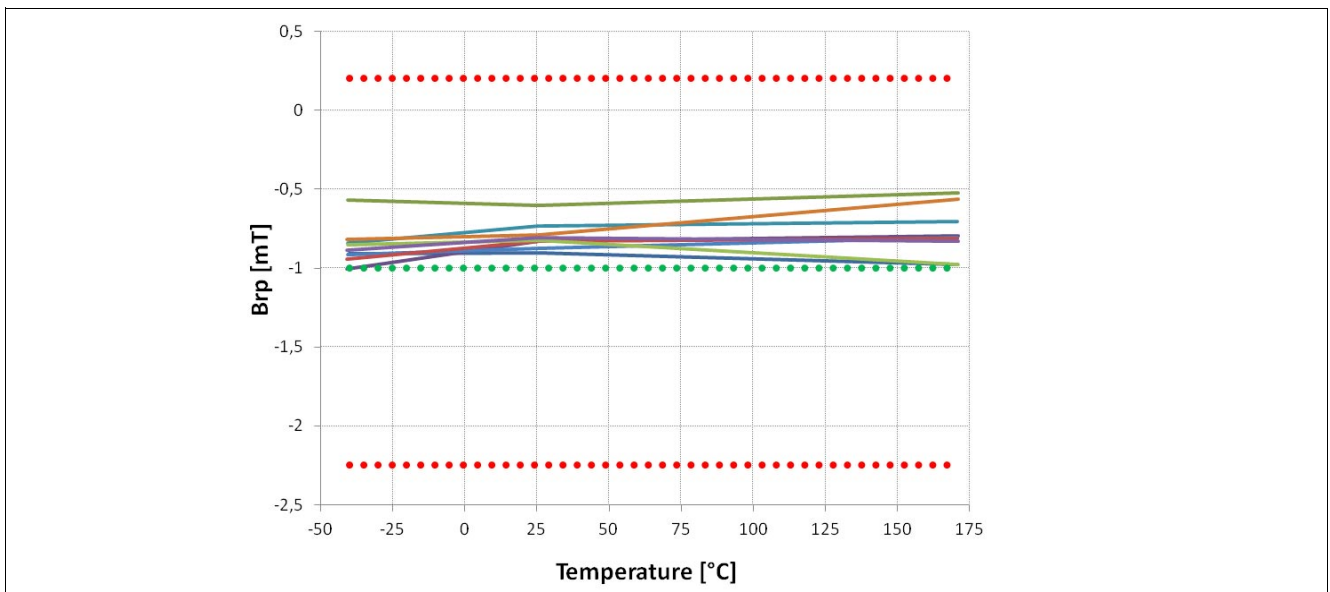


Figure 5-2 Release Point ( $B_{RP}$ ) of the TLE4968-1M over Temperature

Graphs of the Electrical Parameters

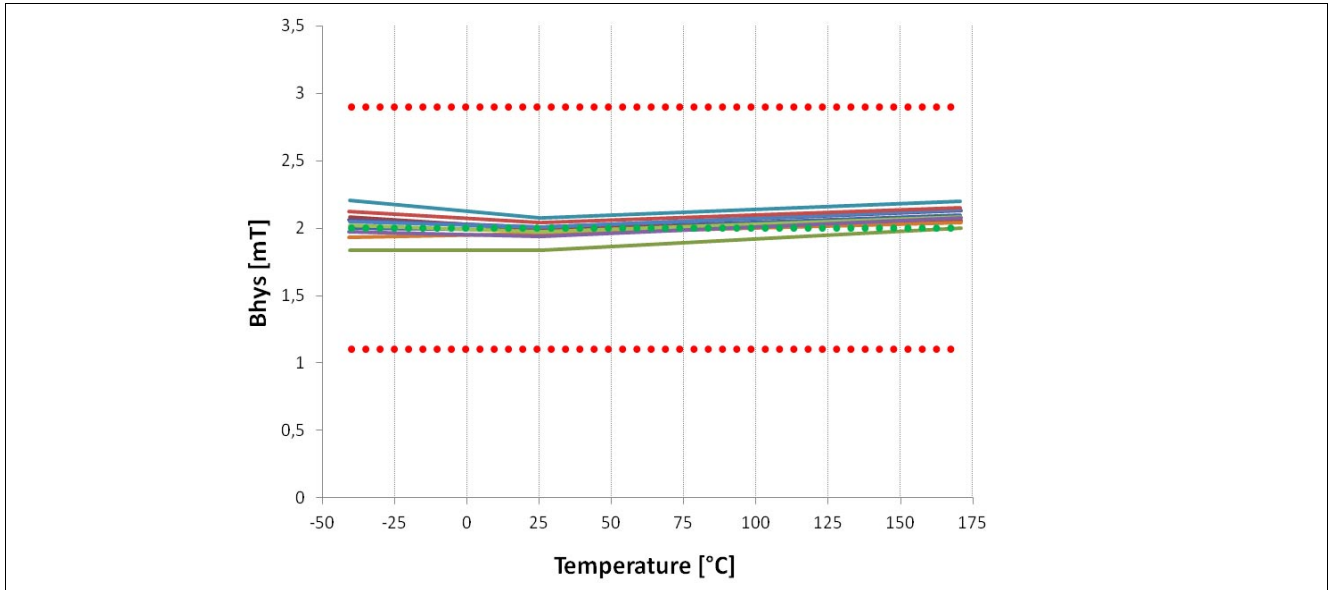


Figure 5-3 Hysteresis ( $B_{Hys}$ ) of the TLE4968-1M over Temperature

## 6 Graphs of the Electrical Parameters

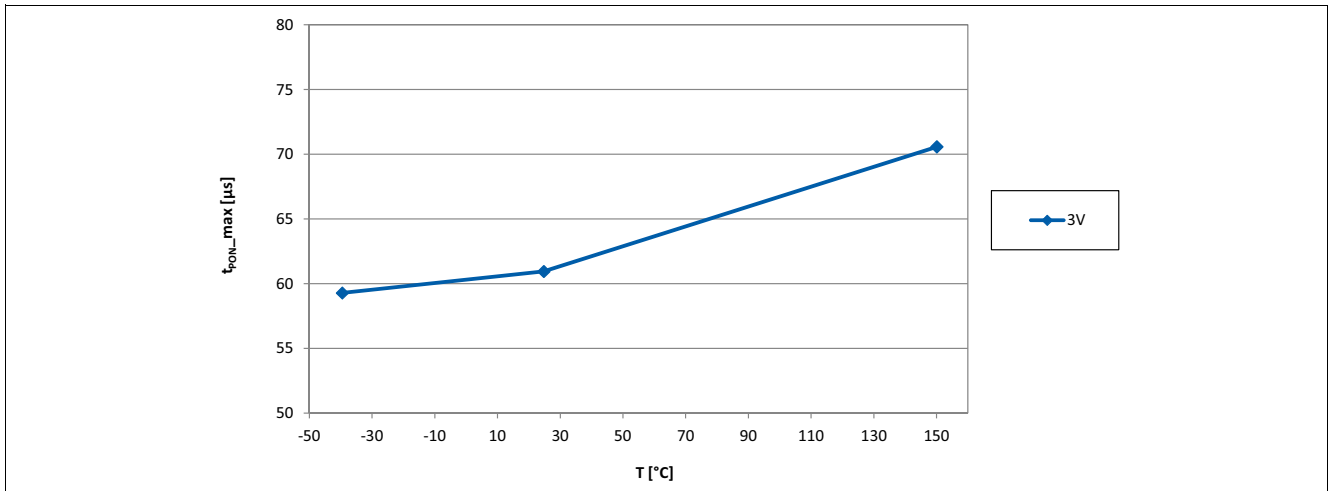


Figure 6-1 Power On Time  $t_{PON}$  of the TLE4968-1M over Temperature

Graphs of the Electrical Parameters

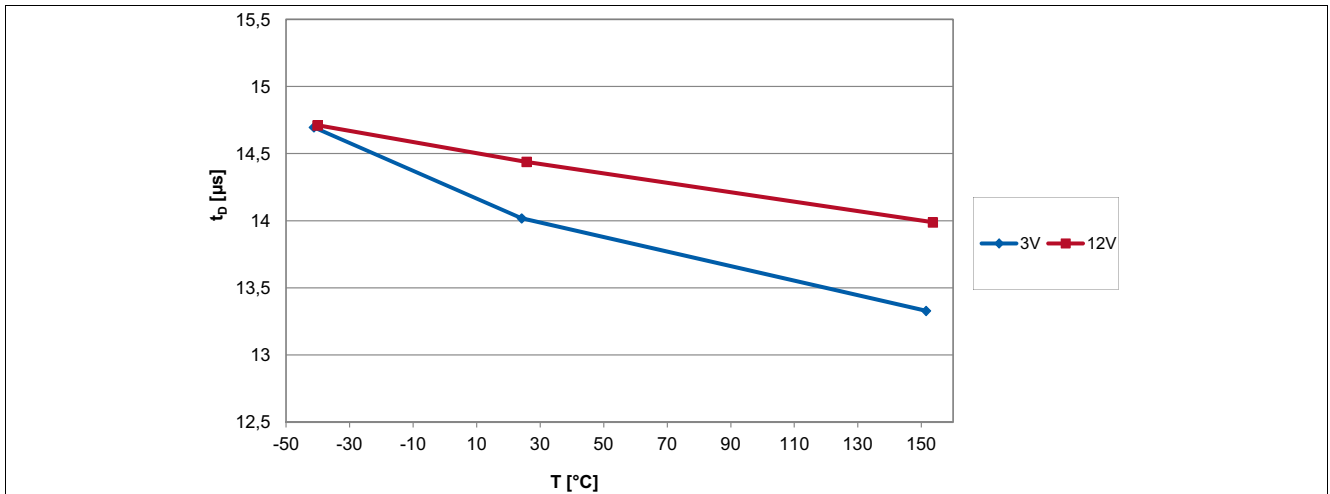


Figure 6-2 Signal Delay Time of the TLE4968-1M over Temperature

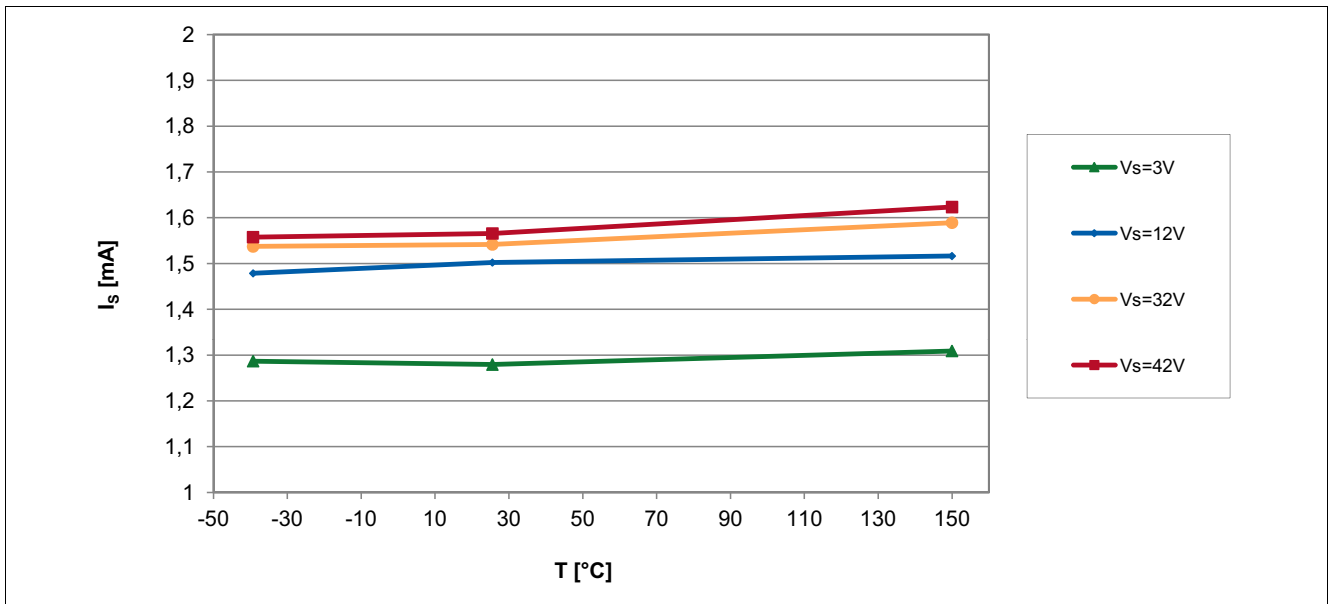


Figure 6-3 Supply Current of the TLE4968-1M over Temperature

Graphs of the Electrical Parameters

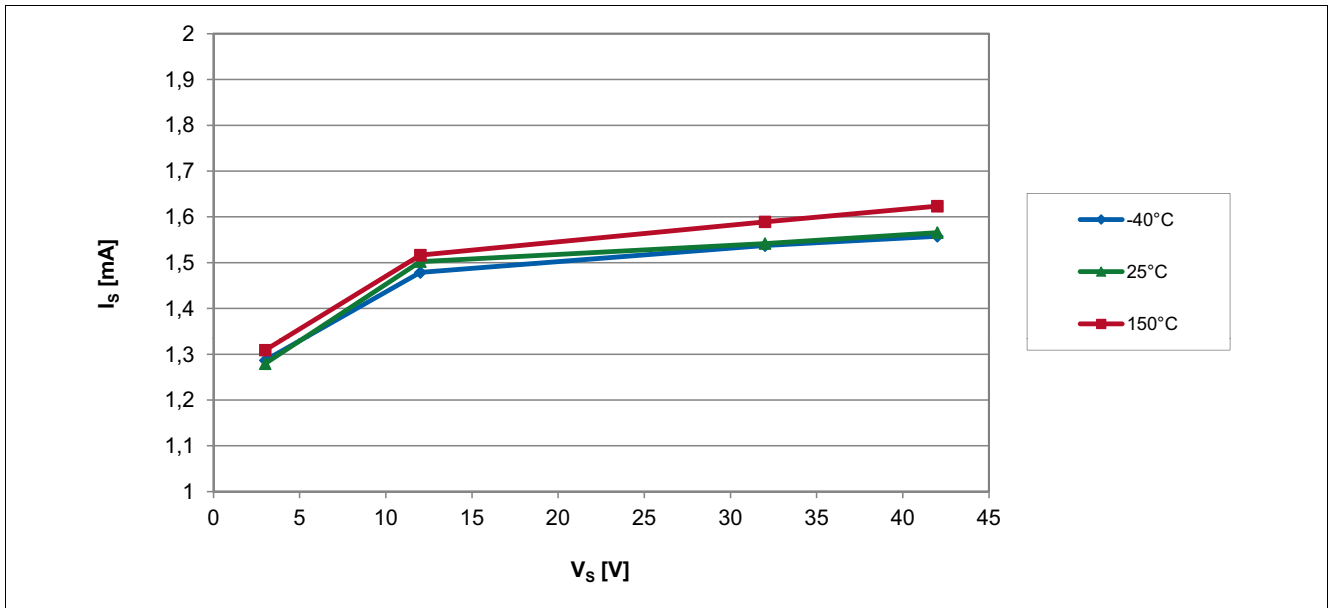


Figure 6-4 Supply Current of the TLE4968-1M over Supply Voltage

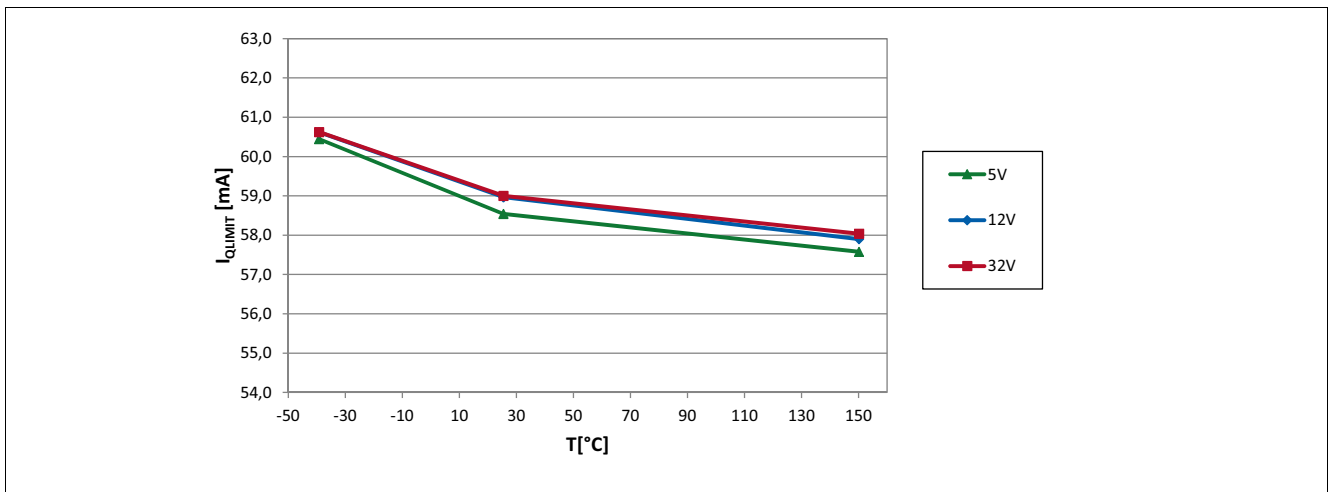


Figure 6-5 Output Current Limit of the TLE4968-1M over Temperature

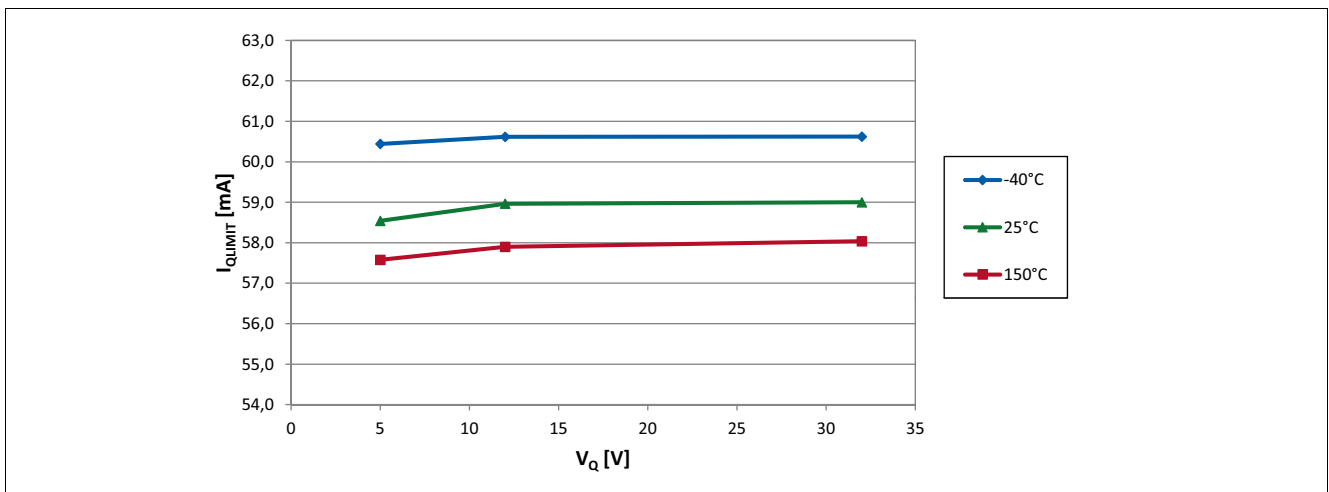


Figure 6-6 Output Current Limit of the TLE4968-1M over applied Pull-up Voltage

Graphs of the Electrical Parameters

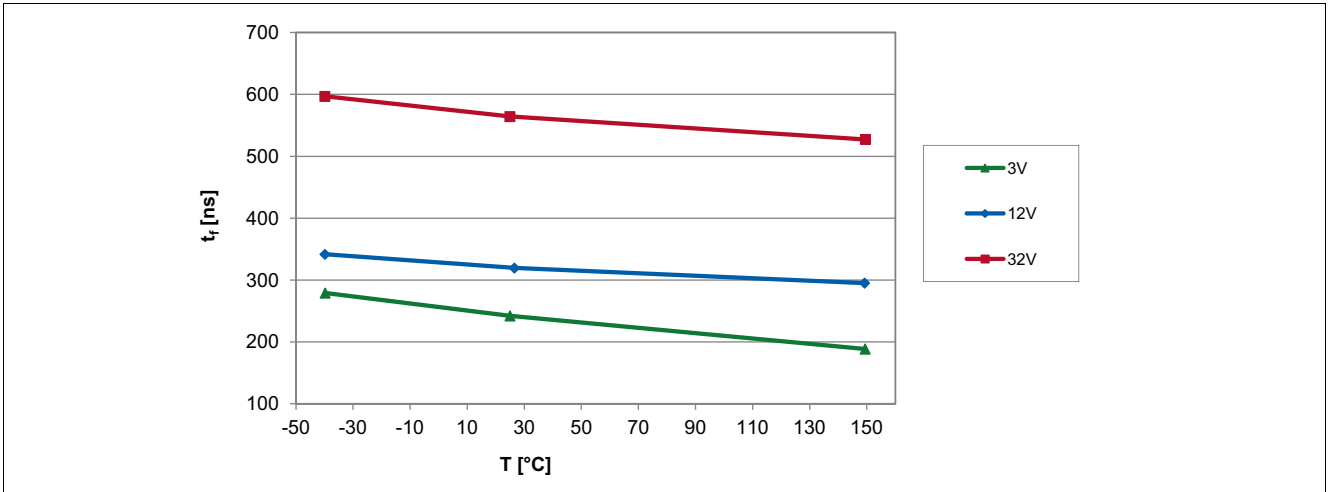


Figure 6-7 Output Fall Time of the TLE4968-1M over Temperature

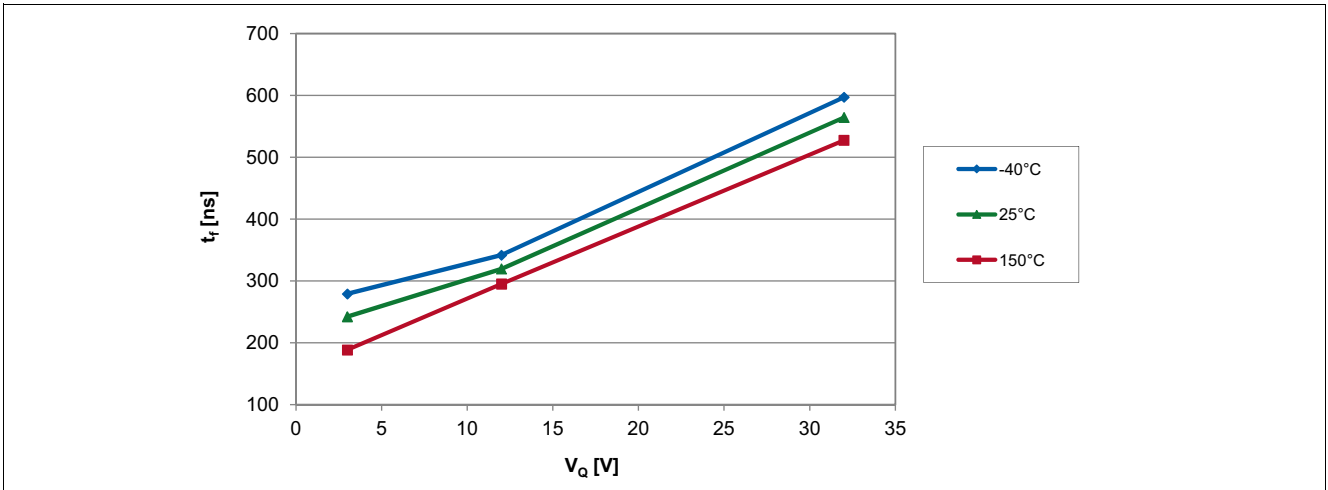


Figure 6-8 Output Fall Time of the TLE4968-1M over applied Pull-up Voltage

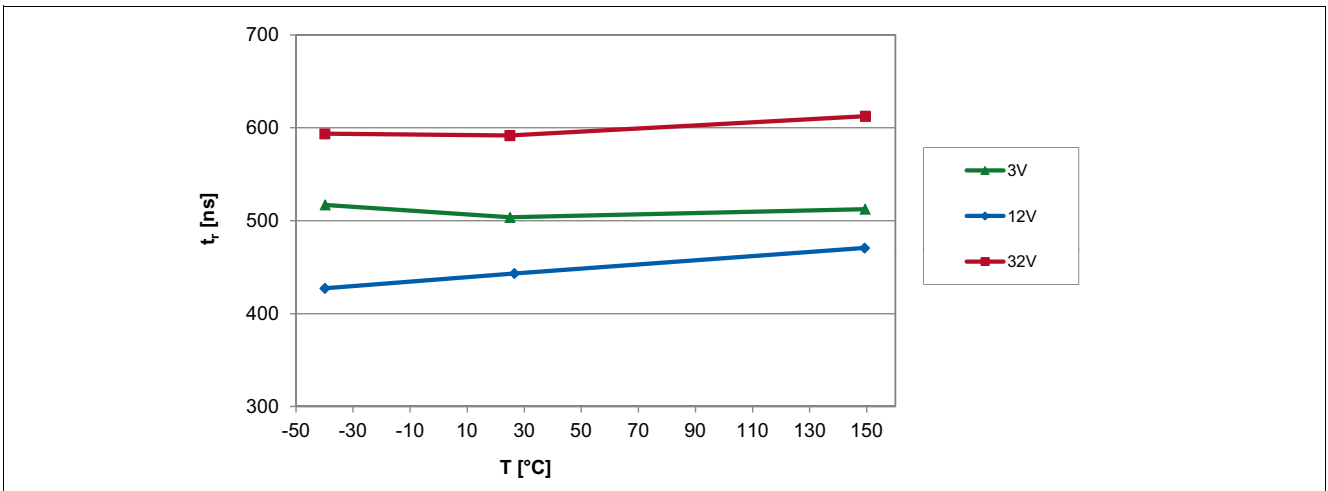


Figure 6-9 Output Rise Time of the TLE4968-1M over Temperature



Graphs of the Electrical Parameters

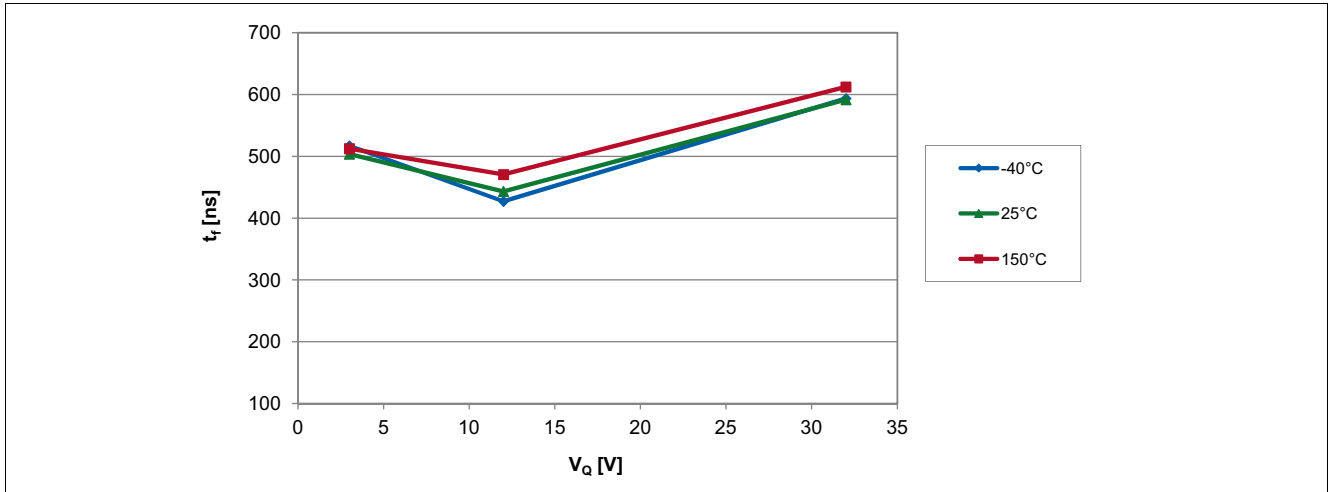


Figure 6-10 Output Rise Time of the TLE4968-1M over applied Pull-up Voltage

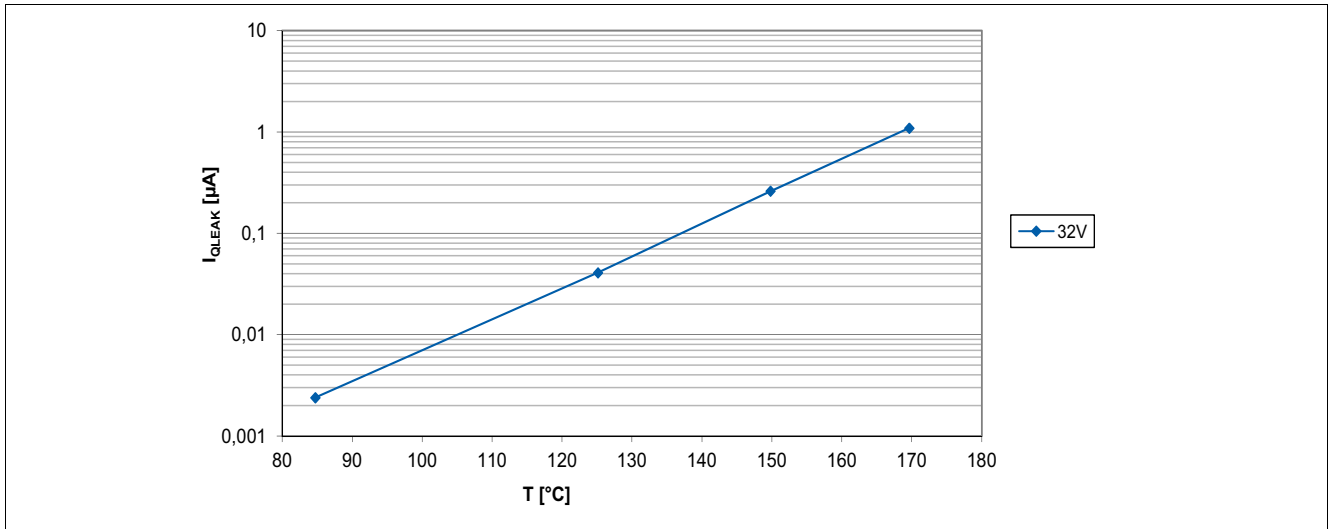


Figure 6-11 Output Leakage Current of the TLE4968-1M over Temperature

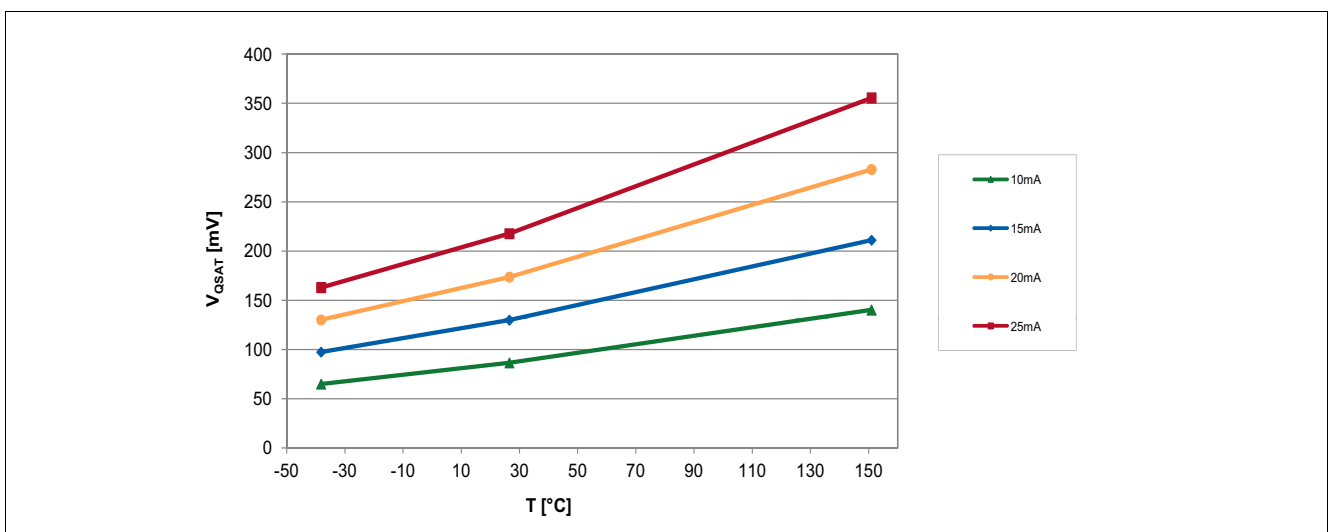


Figure 6-12 Saturation Voltage of the TLE4968-1M over Temperature

Graphs of the Electrical Parameters

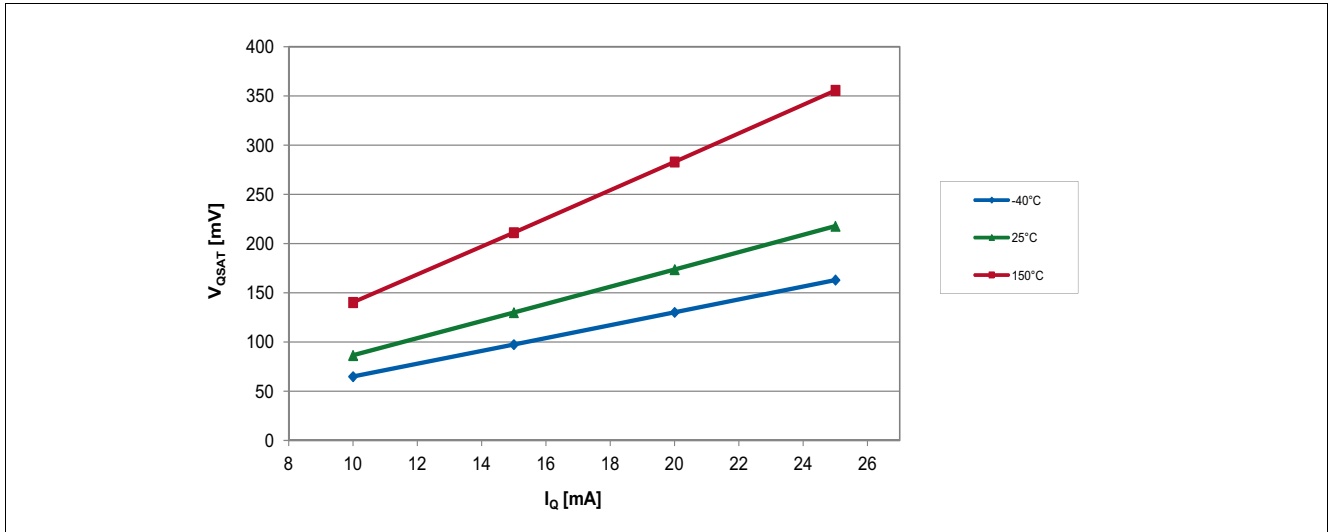


Figure 6-13 Saturation Voltage of the TLE4968-1M over Output Current

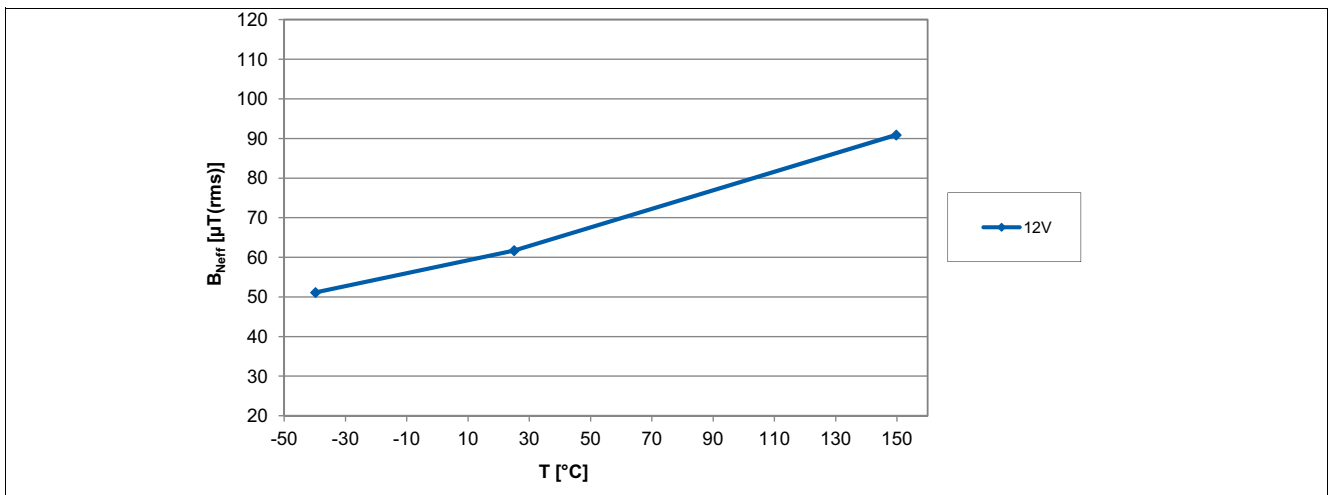


Figure 6-14 Effective Noise of the TLE4968-1M Thresholds over Temperature

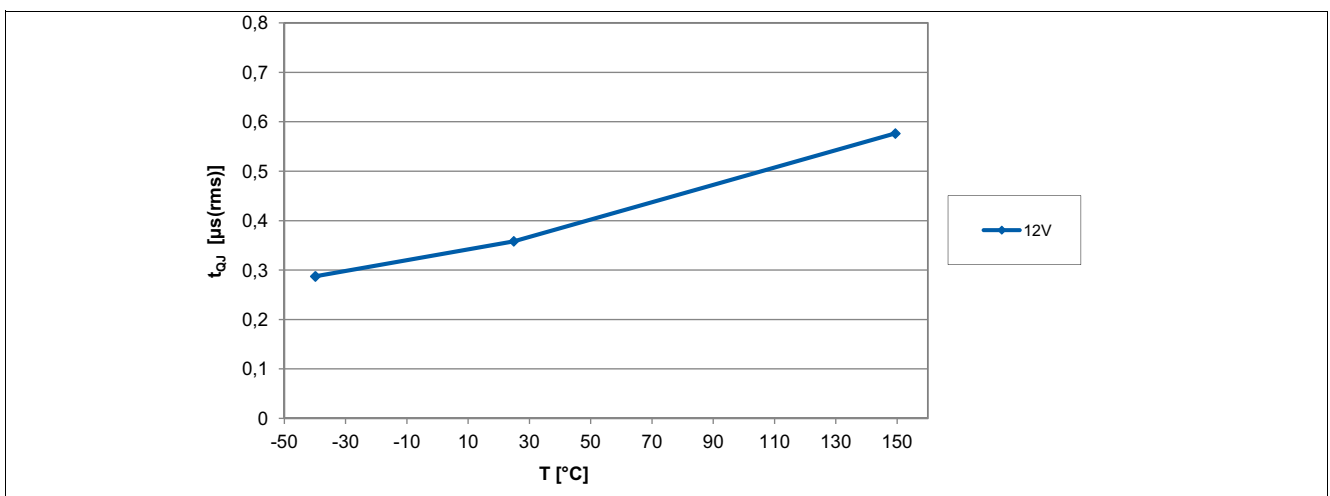


Figure 6-15 Output Signal Jitter of the TLE4968-1M over Temperature